

DOCKET NO.: 93-C-077C2
CLIENT NO.: STMI01-93077
CUSTOMER NO.: 30425

PATENT
DIVISION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: : LOI NGUYEN ET AL.
Serial No. : 09/712,827
Filed : November 14, 2000
For : METHOD AND INTERLEVEL DIELECTRIC STRUCTURE
FOR IMPROVED METAL STEP COVERAGE
Group No. : 2814
Examiner : Long Pham

Mail Stop 16
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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Sir:

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

The undersigned hereby certifies that the following documents:

1. Request for Refund;
2. Copy of Petition Under § 1.181(a)(3) as filed on January 15, 2004 and a copy of the return date-stamped postcard;
3. Copy of Information Disclosure Statement as filed on March 27, 2001 and a copy of the return date-stamped postcard;
4. Copy of Deposit Account Statement dated July 2004; and
5. A return postcard

relating to the above application, were deposited as "First Class Mail" with the United States Postal Service, addressed to Mail Stop 16, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on December 23, 2004.

Date: 12/23/04

Date: Dec. 22, 2004

Nancy J. Todd
Mailer

William A. Munck
William A. Munck
Reg. No. 39,308

P.O. Drawer 800889
Dallas, Texas 75380
Phone: (972) 628-3600
Fax: (972) 628-3616
E-mail: wmunck@davismunck.com

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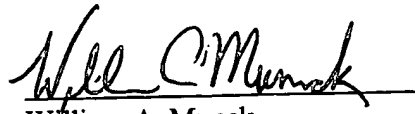
ATTORNEY DOCKET NO.: 93-C-077C1
U.S. SERIAL NO.: 09/712,827
PATENT

Please issue a credit in the amount of \$180.00 to Davis Munck Deposit Account No. 50-0208
for this overpayment.

Respectfully submitted,

DAVIS MUNCK, P.C.

Date: Dec 22, 2004


William A. Munck
Registration No. 39,308

P.O. Drawer 800889
Dallas, Texas 75380
Tel: (972) 628-3600
Fax: (972) 628-3616
E-mail: wmunck@davismunck.com



**United States
Patent and
Trademark Office**

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Deposit Account Statement

Requested Statement Month:

July 2004

Deposit Account Number:

500208

Name:

DAVIS MUNCK

Attention:

JOHN T MOCKLER

Address:

900 THREE GALLERIA TOWER

City:

DALLAS

State:

TX

Zip:

75240

DATE	SEQ	POSTING REF TXT	ATTORNEY DOCKET NBR	FEE CODE	AMT	BAL
07/02	5	10037180	P05023	1501	\$1,330.00	\$4,180.00
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07/08	1	10882690	04-L-014	1001	\$770.00	\$2,610.00
07/08	2	10882690	04-L-014	1201	\$86.00	\$2,524.00
07/08	139	10610373	16217RRUS01U	8007	\$20.00	\$2,504.00
07/08	141	10610517	15995RRUS01	8007	\$20.00	\$2,484.00
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07/29	4	09712827	STMI01-93077	1806	\$180.00	\$5,764.00
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07/30	72	09896796	RFMI01-00001	8011	\$55.00	\$6,061.00
07/30	104	10659907	2003.09.007.WSO	8007	\$20.00	\$6,041.00
07/30	108	10696502	2003.10.004.WSO	8007	\$20.00	\$6,021.00
07/30	137	10703700	2003.10.019.WSO	8007	\$20.00	\$6,001.00
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07/30	220	09729853	CRAN01-00266	8008	\$200.00	\$5,776.00

START
BALANCE
\$5,510.00

SUM OF
CHARGES
\$3,586.00

SUM OF
REPLENISH
BALANCE
\$3,852.00 \$5,776.00

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Mailed:

Jan. 15, 2004

In re. Application of: Loi N. Nguyen, et al

Serial No.: 09/712,827

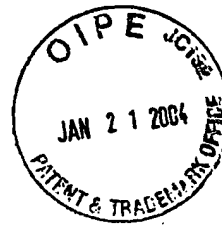
Filing Date: November 14, 2000

Title: METHOD AND INTERLEVEL DIELECTRIC STRUCTURE FOR
IMPROVED METAL STEP COVERAGE

Docket No.: 93-C-077C1 (STMI01-93077)

The following documents were received in the U.S. Patent and Trademark Office on the
date stamped below:

- 1) Certificate of Mailing by First Class Mail; and,
- 2) Petition Under 37 C.F.R. §1.181.



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JAN 30 2004

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JAN 28 2004

DAVIS MUNCK

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Mailed:

Jan. 15, 2004

In re. Application of: Loi N. Nguyen, et al

Serial No.: 09/712,827

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Title: METHOD AND INTERLEVEL DIELECTRIC STRUCTURE FOR
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DOCKET NO. 93-C-077C1 (STMI01-93077)
Customer No. 30425

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: : Loi N. Nguyen, et al.
Serial No. : 09/712,827
Filed : November 14, 2000
For : METHOD AND INTERLEVEL DIELECTRIC
STRUCTURE FOR IMPROVED METAL STEP
COVERAGE
Group No. : 2814
Examiner : L. Pham

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

Sir:

The undersigned hereby certifies that the following documents:

1. Petition Under 37 C.F.R. §1.181;
2. A postcard receipt;

relating to the above application, were deposited as "First Class Mail" with the United States Postal Service, addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on 1/15/04.

Date: 1/15/04

Date: 1-15-04

Kathy Cedar
Mailer
Daniel E. Venglarik
Daniel E. Venglarik
Registration No. 39,409

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E-mail: dvenglarik@davismunck.com

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DOCKET NO. 93-C-077C1 (STMI01-93077)
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PATENT

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COVERAGE
Group No. : 2814
Examiner : L. Pham

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

PETITION UNDER 37 C.F.R. § 1.181

Pursuant to 37 C.F.R. § 1.181(a)(3), Applicants respectfully invoke the supervisory authority of the Commissioner with respect to consideration of the references cited by Applicants in an Information Disclosure Statement filed March 27, 2001.

An Information Disclosure Statement was filed by Applicants pursuant to 37 C.F.R. § 1.56 on March 27, 2001. The Information Disclosure Statement was properly filed with a Form PTO-1449 listing all cited references and copies of each reference cited.

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ATTORNEY DOCKET NO. 93-C077C1 (STMI01-93077)

U.S. SERIAL NO. 09/712,827

PATENT

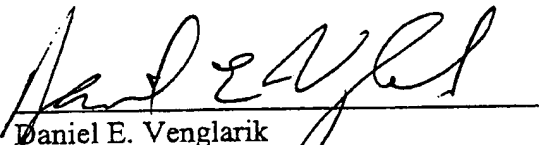
Applicants have unsuccessfully attempted to obtain an initialed Form PTO-1449 for the Information Disclosure Statement indicating consideration of the cited references. Consideration of the cited references and an initialed Form PTO-1449 are respectfully requested.

The Commissioner is hereby authorized to charge any additional fees connected with this communication or credit any overpayment to Deposit Account No. 50-0208.

Respectfully submitted,

DAVIS MUNCK, P.C.

Date: 1-15-04


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Mailed: March 27, 2001
In re. Application of: Loi N. Nguyen, et al
Serial No.: 09/712,827
Filing Date: November 14, 2000
Title: METHOD AND INTERLEVEL DIELECTRIC STRUCTURE FOR
IMPROVED METAL STEP COVERAGE
Docket No.: 93-C-077C1 (STMI01-93077)

The following documents were received in the U.S. Patent and Trademark Office on the date stamped below:

- 1) Information Disclosure Statement;
- 2) Form PTO-1449; and,
- 3) Eleven (11) references as cited on Form PTO-1449.



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APR 08 2001

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APR - 4 2001
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Mailed: March 27, 2001
In re. Application of: Loi N. Nguyen, et al
Serial No.: 09/712,827
Filing Date: November 14, 2000
Title: METHOD AND INTERLEVEL DIELECTRIC STRUCTURE FOR
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Docket No.: 93-C-077C1 (STMI01-93077)

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- 3) Eleven (11) references as cited on Form PTO-1449.

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DOCKET NO. 93-C-077C1 (STMI01-93077)

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Loi N. Nguyen, et al.
U.S. Serial No. : 09/712,827
Filed : November 14, 2000
For : METHOD AND INTERLEVEL DIELECTRIC STRUCTURE
FOR IMPROVED METAL STEP COVERAGE
Group No. : 2835
Examiner : (Not Yet Known)

Commissioner of Patents
and Trademarks
Washington, D. C. 20231

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on 3/27/01 (Date)

KATHY LONGENECKER
(Printed or typed name of person signing the certificate)
Kathy Longenecker
(Signature of the person signing the certificate)

Dear Sir:

INFORMATION DISCLOSURE STATEMENT

Pursuant to the duty of disclosure under 37 C.F.R. § 1.56, Applicant submits this statement. This submittal is made in accordance with 37 C.F.R. §§ 1.97 and 1.98 and § 609 of the Manual of Patent Examining Procedure. The patents, publications and other information herein are listed below and on the attached Form PTO-1449. Copies of the listed references are submitted herewith.

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DOCKET NO. 93-C-077C1 (STMI01-93077)
U.S. SERIAL NO. 09/712,827
PATENT

<u>U.S. Patent No.</u>	<u>Inventor</u>	<u>Date</u>
4,686,000	Heath	Aug. 11, 1987
4,824,767	Chambers, et al.	Apr. 25, 1989
5,063,176	Lee, et al.	Nov. 5, 1991
5,166,088	Ueda, et al.	Nov. 24, 1992
5,266,516	Ho	Nov. 30, 1993

<u>Foreign Patent No.</u>	<u>Country</u>	<u>Date</u>
JP60246675	Japan	December 6, 1985
JP4196486	Japan	July 16, 1992
0 523 856 A2	Europe	January 20, 1993
JP5074958	Japan	March 26, 1993
0 534 130 A1	Europe	March 31, 1993

Publications

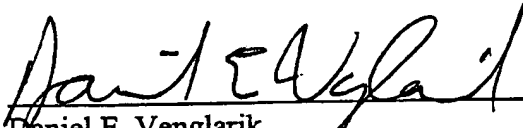
"VLSI Fabrication Principles," by Sorab K. Ghandhi, Rensselaer Polytechnic Institute, A Wiley-Interscience Publication, 1983, pages 479-482; 499-501.

Applicant hereby expressly reserves the right to swear behind the effective dates of any of the above Patents and to question the relevance and materiality of the Patents and Publications listed herein, in whole, in part, or in combination, subsequent to filing this Information Disclosure Statement.

Respectfully submitted,

NOVAKOV DAVIS & MUNCK, P.C.

Date: 3-27-01


Daniel E. Venglarik
Registration No. 39,409

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**DOCKET No. 93-C-077C1 (STMI01-93077)
U.S. SERIAL NO. 09/712,827
PATENT**

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Dallas, Texas 75240
Telephone: (214) 922-9221
Facsimile: (214) 969-7557
email: dvenglarik@novakov.com

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Sheet 1 of 1

FORM PTO-1449 (REV. 7.80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. 93-C-077C1 (STMI01-93077)		SERIAL NO. 09/712,827	
LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Loi N. Nguyen, et al.			
				FILING DATE November 14, 2000		GROUP 2835	
U. S. PATENT DOCUMENTS							
*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (if appropriate)	
AA	4,686,000	08/11/1987	Heath	156	643	Feb. 19, 1986	
AB	4,824,767	04/25/1989	Chambers, et al.	430	313	Jun. 2, 1987	
AC	5,063,176	11/05/1991	Lee, et al.	437	195	May 30, 1990	
AD	5,166,088	11/24/1992	Ueda, et al.	437	47	Jun. 25, 1991	
AE	5,266,516	11/30/1993	Ho	437	57	Jan. 2, 1992	
AF							
AG							
FOREIGN PATENT DOCUMENTS							
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
AH	0 523 856 A2	06/28/91	Europe				
AI	0 534 130 A1	3/31/93	Europe				
AJ	JP60246675	06/12/85	Japan				
AK	JP4196486	07/16/92	Japan				
AL	JP5074958	03/26/93	Japan				
AM							
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)							
AN	"VLSI Fabrication Principles," by Sorab K. Ghandhi, Rensselaer Polytechnic Institute, A Wiley Publication, John Wiley & Sons, 1983, pages 479-482, 499-501.						
AO							
AP							
EXAMINER				DATE CONSIDERED			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line if not in conformance and not considered. Include copy of this form with next communication to applicant.							

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DOCKET NO. 93-C-077C1 (STMI01-93077)
Customer No. 30425

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Serial No. : 09/712,827
Filed : November 14, 2000
For : **METHOD AND INTERLEVEL DIELECTRIC
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COVERAGE**
Group No. : 2814
Examiner : L. Pham

Commissioner for Patents

7/29/2004 P.O. Box 1450
1 FC:1806 Alexandria, VA 22313-1450
180.00 22

Sir:

PETITION UNDER 37 C.F.R. § 1.181

Pursuant to 37 C.F.R. § 1.181(a)(3), Applicants respectfully invoke the supervisory authority of the Commissioner with respect to consideration of the references cited by Applicants in an Information Disclosure Statement filed March 27, 2001.

An Information Disclosure Statement was filed by Applicants pursuant to 37 C.F.R. § 1.56 on March 27, 2001. The Information Disclosure Statement was properly filed with a Form PTO-1449 listing all cited references and copies of each reference cited.

Adjustment date: 02/08/2005 SDIRETA1
07729/2004 GSTANLEY 00000003 500208 09712827
01 FC:1806 180.00 CR